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**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant : Min-Lung HUANG et al. Confirmation No: 8687  
Appl. No. : 10/820,855  
Filed : April 9, 2004  
Title : Under Bump Metallization Structure Of A Semiconductor Wafer

TC/A.U. : 2814  
Examiner : A. Kalam

Docket No.: : HUAN3262/REF  
Customer No: : 23364

**PETITION FOR EXTENSION OF TIME**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

Applicants request that the period for response to the outstanding official action in this case be extended pursuant to 37 CFR 1.136 (a) for ONE (1) month to December 27, 2007.

The fee set in 37 CFR 1.17(a)(1) for a one month extension of time is \$120.00 and a check in this amount is submitted herewith. Please charge any additional fee required for this extension to Deposit Account No. 02-0200.

Respectfully submitted,  
BACON & THOMAS, PLLC

By: Scott A. Brainton  
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December 27, 2007